H1N5820 thru H1N5822

3.0 AMPS. SCHOTTKY BARRIER RECTIFIERS

Features

- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability

Mechanical Data

- Cases: DO-201AD molded plastic.
- Epoxy: UL 94V-0 rate flame retardant.
- Lead: Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Polarity: Color band denotes cathode end.
- High temperature soldering guaranteed: 250°C/10 seconds/.375”(9.5mm) lead lengths at 5 lbs., (2.3Kg) tension.
- Weight: 1.10 grams.

Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Type Number	H1N5820	H1N5821	H1N5822	Units
Maximum Recurrent Peak Reverse Voltage	20	30	40	V
Maximum RMS Voltage	14	21	28	V
Maximum DC Blocking Voltage	20	30	40	V
Maximum Average Forward Rectified Current 0.375"(9.5mm) Lead Length @ TL=90°C	3			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	80			A
Maximum Instantaneous Forward Voltage @ 3A	0.475	0.5	0.525	V
Maximum Instantaneous Forward Voltage @ 9A	0.85	0.9	0.95	V
Maximum DC Reverse Current At Rated DC Blocking Voltage	2 (@ Ta=25°C) 20 (@ Ta=100°C)			mA mA
Typical Thermal Resistance (Note 1) $R\theta JA$	40			°C /W
Typical Junction Capacitance (Note 2)	250			pF
Operating Temperature Range Tj	-65 to +125			°C
Storage Temperature Range TSTG	-65 to +125			°C

Note 1: Thermal resistance from junction to ambient vertical P.C. Board Mounting, 0.375”(9.5mm) lead length.
Note 2: Measured at 1Mhz and applied reverse voltage of 4V D.C.

Characteristics Curve

FIG. 1-MAXIMUM FORWARD CURRENT DERATING CURVE

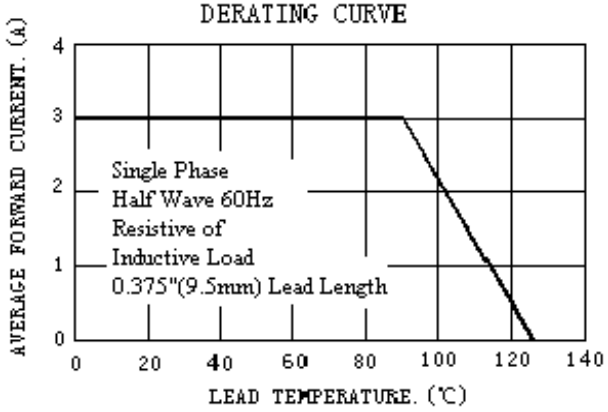


FIG. 2-TYPICAL REVERSE CHARACTERISTICS

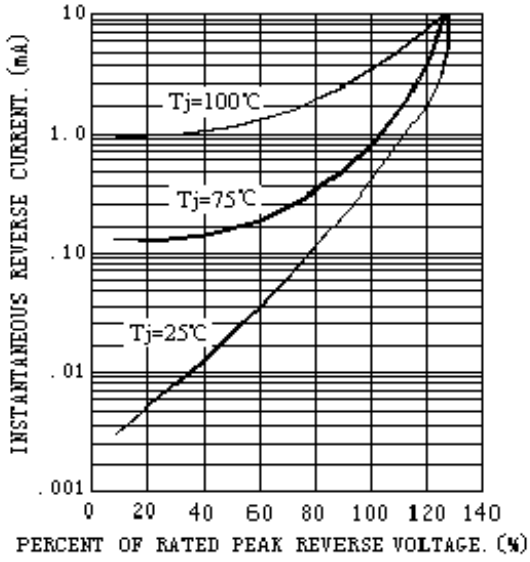


FIG. 3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

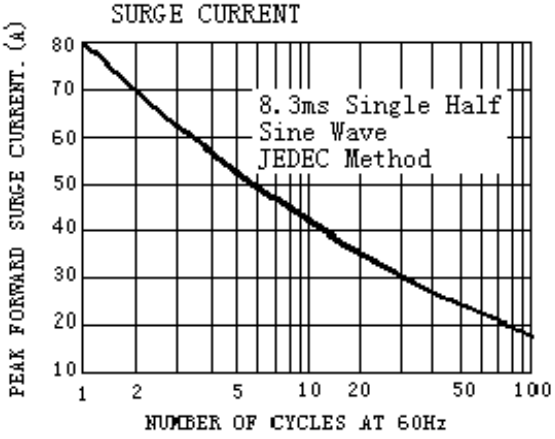


FIG. 4-TYPICAL FORWARD CHARACTERISTICS

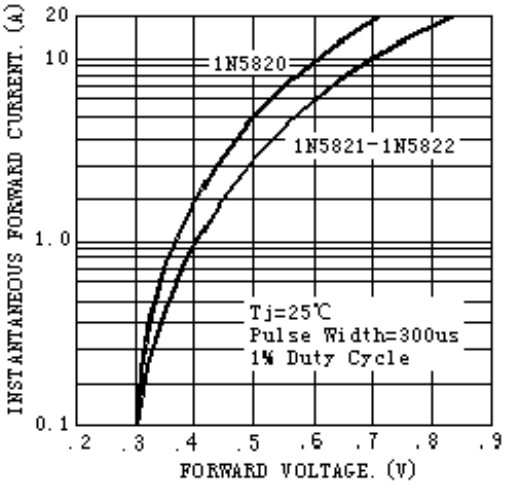
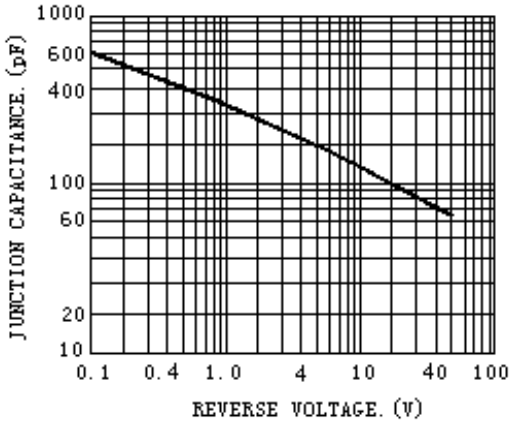
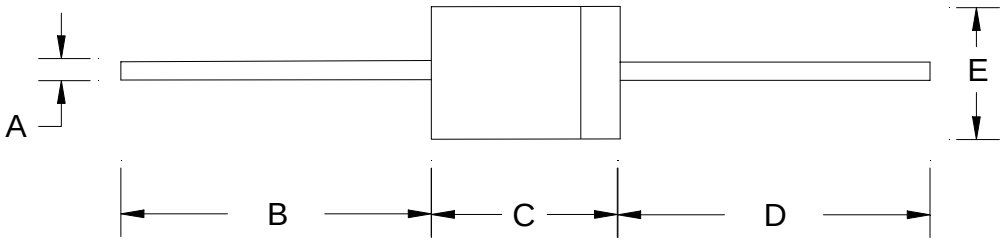


FIG. 5-TYPICAL JUNCTION CAPACITANCE



DO-201 Dimension



DO-201 Molded Plastic Package
HSMC Package Code: L

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0472	0.0512	1.20	1.30	D	1.0000	-	25.40	-
B	1.0000	-	25.40	-	E	0.1890	0.2087	4.80	5.30
C	0.2835	0.3740	7.20	9.50					

Notes : 1.Dimension and tolerance based on our Spec. dated May 28,1998.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed.
- Mold Compound : Epoxy resin family, flammability solid burning class: UL94V-0

Head Office And Factory :

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